

AMENDMENTS TO THE CLAIMS

1. (Cancelled)
2. (Cancelled)
3. (Cancelled)
4. (Cancelled)
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6. (Cancelled)
7. (Cancelled)
8. (Cancelled)
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12. (Cancelled)
13. (Cancelled)
14. (Cancelled)
15. (Cancelled)

16. (Original) A method of connecting an assembly to a printed circuit board, the assembly including a heatsink having a base plate portion and a plurality of fins extending from and integral with the base plate portion, a laser diode having at least one lead, and at least one laser support block, comprising:

connecting the laser diode to the heatsink;

interposing the at least one laser support block between the heatsink and the printed circuit board; and

connecting the heatsink to the printed circuit board, wherein a portion of a connection force connecting the heatsink to the printed circuit board is transferred through the at least one laser support block to couple the at least one lead of the laser diode with at least one pad of the printed circuit board.

17. (Original) A method of connecting an assembly to a printed circuit board as recited in claim 16, wherein the at least one laser support block connects to the heatsink.

18. (Original) A method of connecting an assembly to a printed circuit board as recited in claim 16, wherein the assembly is temporarily connected to the printed circuit board.

19. (Original) A method of connecting an assembly to a printed circuit board as recited in claim 16, further comprising:

connecting a fiber optic cable to the laser diode;

converting an electrical signal provided by the at least one lead into an optical signal in the laser diode; and

providing the optical signal to the fiber optic cable.